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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/810,965	03/26/2004	Yen-Ming Chen	TS01-0413C	9818
47390	7590	11/15/2005	EXAMINER	
THOMAS, KAYDEN, HOSTEMEYER & RISLEY LLP 100 GALLERIA PARKWAY SUITE 1750 ATLANTA, GA 30339			TRINH, HOA B	
			ART UNIT	PAPER NUMBER
				2814

DATE MAILED: 11/15/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

AK

Office Action Summary	Application No.	Applicant(s)
	10/810,965 Examiner Vikki H. Trinh	CHEN ET AL. Art Unit 2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 26 October 2005.
 2a) This action is **FINAL**. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 29-34 and 36-38 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 29-34 and 36-38 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on 26 March 2004 is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
 Paper No(s)/Mail Date _____.
 4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date. _____.
 5) Notice of Informal Patent Application (PTO-152)
 6) Other: _____.

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 10/26/05 has been entered.

Acknowledgement

Applicant filed an amendment on 10/26/05, has been considered. Claims 29-34 and 36-38 are pending in this present application.

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 29, 31, 37-38 are rejected under 35 U.S.C. 102(b) as being anticipated by Marrs (5,795,818).

As to claims 29, and 37-38, Marrs discloses a solder bump for interconnection of a flip chip device comprising a semiconductor surface 501 (fig. 8), a passivation layer 601 (fig. 8) over said semiconductor surface 501; at least a contact pad 501B (fig. 8) created over the semiconductor surface 501; the passivation layer 601 exposing said at least one contact pad 501B; an UBM 502 (fig. 8) created over the at least one contact pad 501B (fig. 8), a lateral dimension of the UBM layer 502 being limited to be within lateral dimension or being limited to a size approx. the same as lateral dimension of the at least one contact pad 501B; and at least one solder compound 312 (fig. 8) overlying the UBM layer, wherein the solder compound comprises a flat top (fig. 8) surface and convex sidewalls (fig. 8) before connecting to other components, wherein the top surface is greater than the bottom surface (fig. 8). Note that the term "over" the at least one pad is interpreted to mean that the UBM has a height dimension that is "over" the height of the at least one pad.

As to claim 31, the UBM layer 502 (col. 9, lines 5-10) comprising a plurality of sub-layers of different metallic composition.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

Art Unit: 2814

1. Determining the scope and contents of the prior art.
2. Ascertaining the differences between the prior art and the claims at issue.
3. Resolving the level of ordinary skill in the pertinent art.
4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

5. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

6. Claims 29-34, 36-38 are rejected under 35 U.S.C. 103(a) as being unpatentable over Marrs in view of Beddingfield (5,977,632).

Marrs discloses a solder bump for interconnection of a flip chip device comprising a semiconductor surface 501 (fig. 8), a passivation layer 601 (fig. 8) over said semiconductor surface 501; at least a contact pad 501B (fig. 8) created over the semiconductor surface 501; the passivation layer 601 exposing said at least one contact pad 501B; an UBM 502 (fig. 8) created over the at least one contact pad 501B (fig. 8), a lateral dimension of the UBM layer 502 being limited to be within lateral dimension or being limited to a size approx. the same as lateral dimension of the at least one contact pad 501B; and at least one solder compound 312 (fig. 8) overlying the UBM layer, wherein the solder compound comprises a flat top (fig. 8) surface and convex sidewalls (fig. 8) before connecting to other components, wherein the top surface is greater than the bottom surface (fig. 8). Note that if the term "over" is to mean that the UBM is

directly contacted over the at least one pad and the passivation layer, then Marrs does not explicitly teach that limitation, as stated in claims 29, 37-38. Also, Marrs does not explicitly teach that the UBM has a layer of chromium followed by a layer of copper followed by a layer of gold, as stated in claim 30.

Beddingfield discloses an analogous device having an UBM 22, 24 (fig. 5) comprising a layer of chromium followed by a layer of copper followed by a layer of gold (col. 3, lines 48-51), wherein the UBM is positioned over the passivation layer 16 and at least one contact pad 12 (fig. 5).

Therefore, as to claims 29, 37-38, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the invention of Marrs with the UBM positioned over and in contact with the at least pad and passivation layer, as taught by Beddingfield, so as to promote adhesion of the solder to the passivation layer and the pad (col. 3, lines 40-45).

As to claim 30, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the invention of Marrs with the UBM having the layer, as taught by Beddingfield, so as to protect against the corrosion of the aluminum pads (col. 3, lines 45-50).

As to claim 31, Marrs teaches the UBM layer 502 (col. 9, lines 5-10) comprising a plurality of sub-layers of different metallic composition.

As to claim 32, Beddingfiled teaches the passivation layer has a plurality of passivation layers 16, 18, 20 (fig. 5).

As to claim 33, Beddingfiled teaches the plurality of passivation layers 16, 18, 20 (fig. 5) are photosensitive polyimide (col. 3, lines 5-10).

As to claim 34, Beddingfiled teaches the at least one contact pad 12, 13 (fig. 5) being electrically connected with “a” semiconductor device with at least one conductive line of interconnect or with one conductive contact point (fig. 5)

As to claim 36, Beddingfiled teaches that a seed layer 18, 20 (fig. 5) is deposited over the patterned layer of passivation 16 (fig. 5).

Response to Arguments

7. Applicant's arguments filed 10/26/05 have been fully considered but they are moot in view of the new rejection.

Conclusion

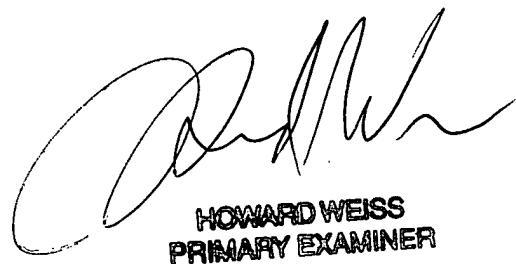
Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Vikki Trinh whose telephone number is (571) 272-1719. The Examiner can normally be reached from Monday-Friday, 9:00 AM - 5:30 PM Eastern Time. If attempts to reach the examiner by telephone are unsuccessful, the Examiner's supervisor, Mr. Wael Fahmy, can be reached at (571) 272-1705. The office fax number is 703-872-9306.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. If you have questions

pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site (www.uspto.gov), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at <http://www.uspto.gov/ebc/index.html> or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, *WT*
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AU 2814



HOWARD WEISS
PRIMARY EXAMINER